

TECHNICAL DATA

DIRECTBOND

Direct Diode Laser System for Thermal Processing

Wavelength: 808 nm
Power: 30 W, 60 W

**FEATURES**

- Turn Key System
- 19" Rack-Mounted
- Air-Cooled
- Thermal Management
- Industrial Delivery Fiber
- Microprocessor Operation
- Serial, Analog and TTL Control
- Graphical User Interface

APPLICATIONS

Ideally Suited for High-Throughput Industrial Applications:

- FRIT Welding of OLED Displays
- Thermal Processing Tasks:
 - Soldering
 - Plastics Welding

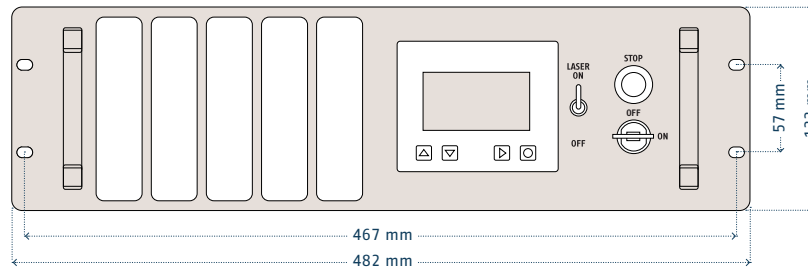
DIRECTBOND

Direct Diode
Laser System
for Thermal
Processing

TECHNICAL SPECIFICATIONS

Output Power, Fiber Coupled	W	30	60
Wavelength	nm	808	
Linewidth, Typical FWHM	nm	3	
Wavelength Tolerance	nm	± 3	
Fiber Size	µm	200	400
Numerical Aperture		0.22	
Fiber Length, Other on Request	m	3	
Fiber Connector (out)		SMA	
Supply voltage	V	110 - 230	
Dimensions (L x W x H)	mm (inch)	266 x 482 x 113 (10 x 19 x 5)	
Humidity @ 25°C		< 75%	
Operating Temperature Range	°C	10 - 45	
Storage Temperature	°C	5 - 50	
Cooling		forced air	

Front view



Rear view

